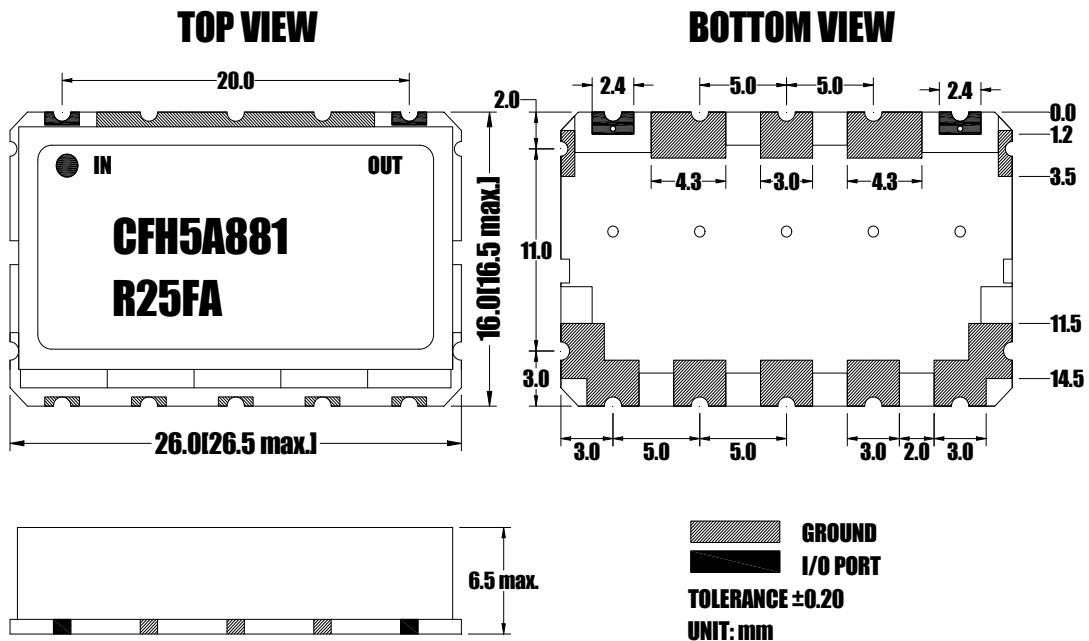


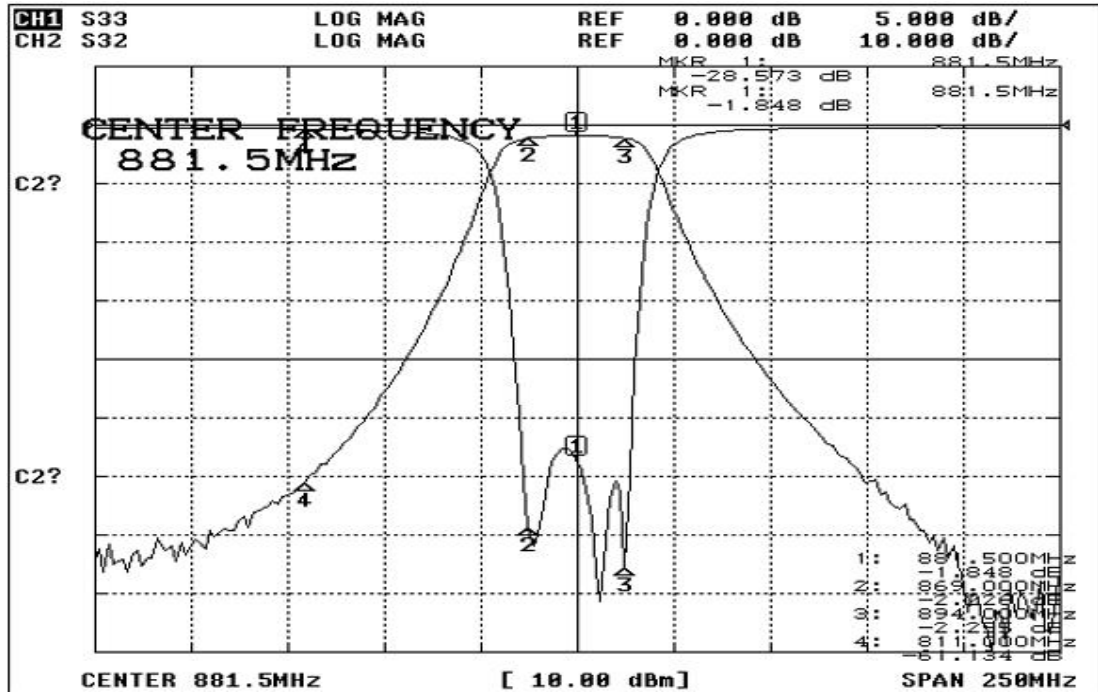
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	881.5	MHz
Bandwidth [BW]	$f_o \pm 12.5$ [869~ 894]	MHz
Insertion Loss in BW	3.0	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	16.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	dB min @ $f_o - 70.5$ [811]	MHz
	dB min @ $f_o \pm [\sim]$	MHz
	dB min @ $f_o \pm [\sim]$	MHz
	dB min @ $f_o \pm [\sim]$	MHz
Group Delay Variation		ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

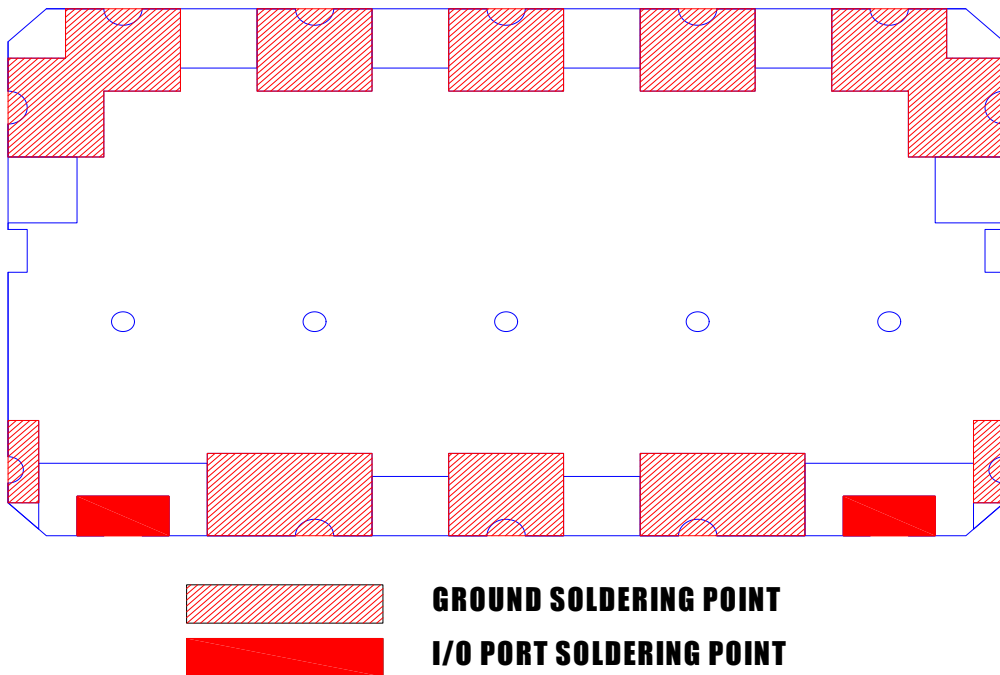
Mechanical Specification



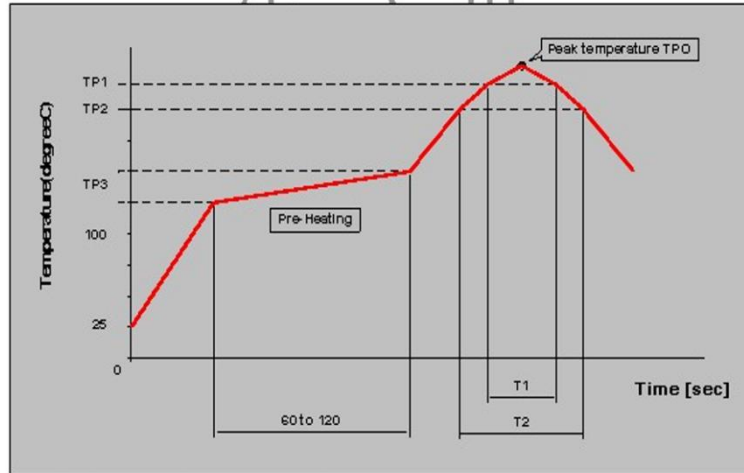
Plot Data



Recommended PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/0	240	20	220	70	150 to 180